

Overview

HP Pro Mini 260 G9 Desktop PC



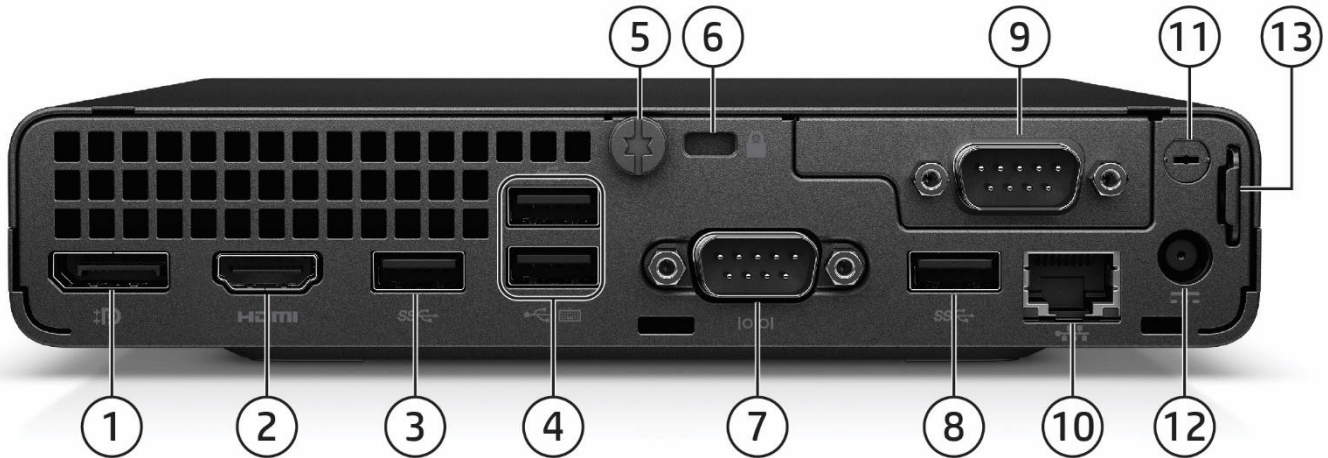
1. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-A SuperSpeed USB 5Gbps signaling rate port
3. Type-A Hi-Speed USB 480Mbps signaling rate port (charge support up to 5V/1.5A)
4. Combo Audio Jack with CTIA and OMTP headset support
5. Dual-state power button
6. Hard drive activity light

Not shown

- (2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280 socket for storage)
- (1) 2.5" internal storage drive bay

Overview

HP Pro Mini 260 G9 Desktop PC



1. DisplayPort™ 1.4a (DP++)
2. HDMI 1.4b
3. Type-A SuperSpeed USB 5Gbps signaling rate port
4. Type-A Hi-Speed USB 480Mbps signaling rate port (2)
5. Cover release thumbscrew
6. Standard cable lock slot (10 mm)
7. Serial port
8. Type-A SuperSpeed USB 5Gbps signaling rate port
9. Flex Port 2¹, choice of:
 - Serial
 - 2nd External Antenna
10. RJ45 Network connector
11. External WLAN antenna opening
12. Power connector
13. Retractable Padlock loop

1. Must be configured at time of purchase

AT A GLANCE

- 12th and 13th Generation Intel® processors (up to Core™ i5), featuring integrated Intel® UHD Graphics
- Choice of Windows 11 Professional, Windows 11 Home, Win 11 Pro 64 Downgrade (Win 10 Pro 64) and FreeDOS Up to 64GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Optional M.2 PCIe NVMe solid state drives (SSD) enabling faster system startup and application launches
- Support for up to two monitors via one standard HDMI 1.4b and one standard Display Port 1.4a.
- Serial port support comes standard, with ability to configure one additional for a total of two, enabling support for legacy peripherals
- Integrated 10/100/1000 Ethernet Controller
- Optional Wi-Fi 6E, Wi-Fi 6 and Wi-Fi 5 (802.11ac) connectivity
- Trusted Platform Module (TPM) 2.0
- VESA mounting incorporated into chassis design
- Dust filter available
- High efficiency energy saving power supply
- PC chassis and all internal components and modules are manufactured with low halogen content
- Protected by HP Services, including limited warranties up to 1-1-1 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 / UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled

Windows 11 Pro¹
Windows 11 Pro Education¹
Windows 11 Home - HP recommends Windows 11 Pro for business¹
Windows 11 Home Single Language - HP recommends Windows 11 Pro for business¹
Windows 10 Pro (available through downgrade rights from Windows 11 Pro)¹
Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume Licensing Agreement)^{1,2}
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

PROCESSORS

Intel® 12th Generation Core™ Processors

Intel® Core™ i5-1235U Processor¹

15W

1.3GHz base frequency

Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²

12MB cache, 10 cores, 12 threads

Intel® Iris® Xe Graphics³

Intel® Core™ i3-1215U Processor¹

15W

1.2GHz base frequency

Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²

10MB cache, 6 cores, 8 threads

Intel® UHD Graphics

Intel® Pentium® Processors

Intel® Pentium® Gold 8505 Processor¹

15W

1.2 GHz base frequency

Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²

8MB cache, 5 cores, 6 threads

Intel® UHD Graphics

Intel® Celeron® Processors

Intel® Celeron® 7305 Processor¹

15W

1.1 GHz base frequency

8MB cache, 5 cores, 6 threads

Intel® UHD Graphics

Standard Features and Configurable Modules

Intel® 13th Generation Core™ Processors

Intel® Core™ i5-1335U Processor¹

15W

1.3GHz base frequency

Up to 4.6 GHz max. Turbo frequency with Intel® Turbo Boost Technology²

12MB cache, 10 cores, 12 threads

Intel® Iris® Xe Graphics³

Intel® Core™ i5-1334U Processor¹

15W

1.3GHz base frequency

Up to 3.4 GHz max Turbo frequency with Intel® Turbo Boost Technology²

12 MB cache, 10 cores, 12 threads

Intel® Iris® Xe Graphics³

Intel® Core™ i3-1315U Processor¹

15W

1.2GHz base frequency

Up to 4.5 GHz max. Turbo frequency with Intel® Turbo Boost Technology²

10MB cache, 6 cores, 8 threads

Intel® UHD Graphics

1. Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.

3. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

GRAPHICS

Integrated

Intel® UHD Graphics, Intel® Iris® Xe Graphics^{1,2}

NOTE: Intel® integrated UHD Graphics varies by processor

1. Intel® Iris® Xe Graphics¹ only support on Intel® Core™ i5-1245U, i5-1235U & i5-1335U.

2. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

2.5 inch SATA Hard Disk Drives (HDD)

1TB* 7200RPM 2.5in SATA HDD

M.2 PCIe NVMe Solid State Drives (SSD)

256GB* M.2 2280 PCIe NVMe SSD

512GB* M.2 2280 PCIe NVMe SSD



Standard Features and Configurable Modules

1TB* M.2 2280 PCIe NVMe SSD
512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD
1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD
2TB* M.2 2280 PCIe NVMe Three Layer Cell SSD
256GB* M.2 2280 PCIe NVMe Self Encrypted OPAL2 SSD**
256GB* M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**
512GB* M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**

***NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

****NOTE:** Storage DriveLock does not work with Self Encrypting or Optane based storage.

MEMORY

Type

DDR4-3200(Transfer rates up to 3200MT/s)

Maximum

64GB capacity

Memory Configurations

2 SODIMMs

4GB (4GB x 1)

8GB (4GB x 2)¹

8GB (8GB x 1)

16GB (8GB x 2)¹

16GB (16GB x 1)

32GB (16GB x 2)¹

32GB (32GB x 1)

64GB (32GB x 2)

1. For Dual channel memory, due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

NOTE: Memory modules support data transfer rates up to 3200 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Networking

Intel® I219-V Gigabit Network Connection LOM (Non-vPro)

Wireless

Realtek RTL8821CE Wi-Fi 5¹ (802.11ac) 1x1 with Bluetooth® 4.2 Wireless Card

Intel® Wi-Fi 6E² AX211 802.11ax 2x2³ with Bluetooth® 5.3 Wireless Card non-vPro™

Realtek RTL 8852BE Wi-Fi 6⁴ with Bluetooth 5.3 Wireless Card

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E



Standard Features and Configurable Modules

is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

3. Usage of the 6GHz band relies on Windows 11 Operating System support.

4. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

NOTE: WiFi-6E might restrict by local regulation and the current eligible regions are: USA, South Korea, Costa Rica, El Salvador, Guatemala, Honduras, Peru and UAE. HP will enable countries in the future by upgrading BIOS in default.

Standard Features and Configurable Modules

KEYBOARDS/POINTING DEVICES

Keyboard and Mouse Combo

HP 655 Wireless Keyboard and Mouse Combo

Keyboard

HP 125 Wired Keyboard

HP USB Business Slim Wired SmartCard CCID Keyboard

Mouse

HP Wired Desktop 320M Mouse

HP Wired 125 Mouse

HP Wired 128 Laser Mouse

NOTE: Availability may vary by country

SECURITY

TPM 2.0¹ (FW: 15.23) endpoint security controller (Infineon SLB9672). Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.

Intrusion Sensor (integrated in the system board, can be enabled/disabled through BIOS)

Support for chassis cable lock devices

Support for chassis padlocks devices

SATA port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Removable media write/boot control

Power-on password (via BIOS)

Setup password (via BIOS)

1. In some scenarios, machines pre-configured with Windows OS might ship with TPM turned off

PORTS

Internal slots and Ports

(1) M.2 PCIe x1 2230 (for WLAN)

(1) M.2 PCIe x4 2280 (for storage)

(1) Integrated SATA storage connector

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Bays

2.5" Internal Storage Drive

Standard User Accessible Ports

Front

- (1) Type-C® SuperSpeed USB 10Gbps signaling rate port
- (1) Type-A Hi-Speed USB 480Mbps signaling rate port
- (1) Type-A SuperSpeed USB 5Gbps signaling rate port
- (1) Combo Audio Jack with CTIA and OMTP headset support

Standard Features and Configurable Modules

Rear

- (2) Type-A SuperSpeed USB 5Gbps signaling rate port
- (2) Type-A Hi-Speed USB 480Mbps signaling rate port
- (1) Display Port 1.4a
- (1) HDMI 1.4b
- (1) RJ45
- (1) Serial (RS-232)

Configurable Non-PCIe/PCI Slot User Accessible Ports

Rear Flexible Port, choice of Serial (RS-232), 2nd External antenna

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Desktop Support Utilities
myHP
HP Notifications
HP Support Assistant¹
HP Smart Support²
Microsoft 365³

Manageability Features

HP Cloud Recovery⁴

Client Security Software

McAfee LiveSafe™ (1 year subscription)⁵

BIOS

UEFI Self Certification Level: 2.9

1. HP Support Assistant requires Windows and Internet access.

2. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit <http://www.hp.com/smart-support..>

3. Sold separately and requires Internet access for activation

4. HP Cloud Recovery is available for select HP desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/document/c05115630>.

5 Availability may vary by country. McAfee LiveSafe 30-day free trial offer (Internet access required. First 30 days included. Subscription required for live updates afterwards.)

Standard Features and Configurable Modules

UNIT ENVIRONMENT AND OPERATING CONDITIONS

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <http://www.epeat.net> for more information.
Low halogen (chassis, all internal components and modules)¹
TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating:	50° to 95° F (10° to 35° C) ²
	Non-operating:	-22° to 140° F (-30° to 60° C)
Relative Humidity	Operating:	10% to 90% (non-condensing at ambient)
	Non-operating:	0% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating:	10,000 ft (3048 m)
	Non-operating:	30,000 ft (9144 m)

2. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Standard Features and Configurable Modules

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a “Typically Configured Desktop”.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	4.9000 W	5.0100 W	4.7000 W
Normal Operation (Long idle)	1.3700 W	1.4500 W	1.2100 W
Sleep	1.3500 W	1.4300 W	1.1900 W
Off	0.5000 W	0.5200 W	0.4600 W
	<p>NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	16.7090 BTU/hr	17.0841 BTU/hr	16.0270 BTU/hr
Normal Operation (Long idle)	4.6717 BTU/hr	4.9445 BTU/hr	4.1261 BTU/hr
Sleep	4.6035 BTU/hr	4.8763 BTU/hr	4.0579 BTU/hr
Off	1.7050 BTU/hr	1.7732 BTU/hr	1.5686 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	2.7	17	
Fixed Disk – Random writes	2.9	17	

Standard Features and Configurable Modules

Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <ul style="list-style-type: none"> • 2 SODIMM memory slots • Interchangeable M.2 PCIe NVME SSD & 2.5" SATA HDD <p>Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Corrugated	450 g
		PAPER/Molded Pulp	74 g
	Internal:	PLASTIC/Polyethylene low density - LDPE	5 g
	The plastic packaging material contains at least 30% recycled content.		
	The corrugated paper packaging materials contains at least 35% recycled content.		
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances 		

Standard Features and Configurable Modules

	<ul style="list-style-type: none"> • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p>
HP Inc. Corporate Environmental Information	<p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

SERVICE AND SUPPORT

On-site Warranty¹: Three-year (3-3-3) or one-year (1-1-1) limited warranty delivers three years or one year of on-site, next business day² service for parts and labor and includes free support 24 x 7³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.⁴

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

GRAPHICS

Intel® UHD Graphics (integrated)¹

Graphics Controller	Integrated
HDMI	Supports HDMI 1.4b features Supports HDCP 2.3 Supports audio over HDMI
DisplayPort	Supports DisplayPort 1.4a
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 16 bits/color
Graphics/Video API Support	HEVC 10b Enc/12b Dec HW VP9 12b Dec HW HDR Rec. 2020 DX12
Max. Resolution (DP)	4096 x 2304@60Hz
Max. Resolution (HDMI)	4096 x 2160 @ 30Hz

Technical Specifications – Storage

STORAGE

NOTE: Starting from November 1ST, 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

500GB 7200RPM 2.5in SATA HDD

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283in/7.2mm (Max)
Width	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.283in/7.2 mm (Max)
Width	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB 5400RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128MB
Logical Blocks	1,953,525,168
Seek Time	12ms (Average)
Height	0.283in/7.2mm (Max.)
Width	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)



Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

2TB 5400RPM 2.5in SATA HDD

Capacity	2TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128MB
Logical Blocks	3,907,050,336
Seek Time	12 ms (Average)
Height	0.374in/9.5mm (Max.)
Width (nominal)	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Capacity	256GB
Interface	PCIe NVMe
Minimum Sequential Read	3200MB/s ±10%
Minimum Sequential Write	2000MB/s ±10%
Logical Blocks	500,118,192
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Capacity	512GB
Interface	PCIe NVMe
Minimum Sequential Read	3200MB/s ±10%
Minimum Sequential Write	3200MB/s ±10%
Logical Blocks	1,000,215,216
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

1TB M.2 2280 PCIe NVMe SSD

Capacity	1TB
Interface	PCIe NVMe
Minimum Sequential Read	3200MB/s $\pm 10\%$
Minimum Sequential Write	3200MB/s $\pm 10\%$
Logical Blocks	2,000,409,264
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity	256GB
Interface	PCIe Gen4x4
Minimum Sequential Read	4000MB/s $\pm 10\%$
Minimum Sequential Write	2000MB/s $\pm 10\%$
Logical Blocks	500,118,192
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity	512GB
Interface	PCIe Gen4x4
Minimum Sequential Read	6400MB/s $\pm 10\%$
Minimum Sequential Write	3500MB/s $\pm 10\%$
Logical Blocks	1,000,215,216
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity	1TB
Interface	PCIe Gen4x4
Minimum Sequential Read	6400MB/s $\pm 10\%$
Minimum Sequential Write	5000MB/s $\pm 10\%$
Logical Blocks	2,000,409,264
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity	2TB
Interface	PCIe Gen4x4
Minimum Sequential Read	6400MB/s $\pm 10\%$
Minimum Sequential Write	5000MB/s $\pm 10\%$
Logical Blocks	4,000,797,360
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Capacity	256GB
Interface	PCIe Gen4x4
Minimum Sequential Read	4000MB/s $\pm 10\%$
Minimum Sequential Write	2000MB/s $\pm 10\%$
Logical Blocks	500,118,192
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Capacity	512GB
Interface	PCIe Gen4x4
Minimum Sequential Read	6400MB/s $\pm 10\%$
Minimum Sequential Write	3500MB/s $\pm 10\%$
Logical Blocks	1,000,215,216
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

NETWORKING AND COMMUNICATIONS

Intel® I219v 1 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BASE-T IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode only) Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® non vPro™ support with appropriate Intel® chipset components

Technical Specifications – Networking

Intel® AX211 Wi-Fi 6E +Bluetooth® 5.3 Wireless Card M.2 160MHz CNVi WW WLAN ¹	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz • 5.955 – 6.415 GHz • 6.435 – 6.515 GHz • 6.535 – 6.875 GHz • 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac: 1733Mbps • 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security²	• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power³	• 802.11b: +17dBm minimum • 802.11g: +16dBm minimum • 802.11a: +17dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +13dBm minimum

Technical Specifications – Networking

	<ul style="list-style-type: none"> • 802.11n HT20(5GHz): +14dBm minimum • 802.11n HT40(5GHz): +13dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum • 802.11ac VHT160(5GHz): +10dBm minimum • 802.11ax HE40(2.4GHz): +12dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum • 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0(VHT80): -84dBm maximum • 802.11ac, MCS9(VHT80): -59dBm maximum • 802.11ac, MCS9(VHT160): -58.5dBm maximum • 802.11ax, MCS11(HE40): -57dBm maximum • 802.11ax, MCS11(HE80): -54dBm maximum • 802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels

Technical Specifications – Networking

	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Usage of the 6GHz band relies on Windows 11 Operating System support.

Technical Specifications – Networking

Realtek 802.11a/b/g/n/ac (1x1) Wi-Fi 5 and Bluetooth® 4.2 Wireless Card¹	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 150Mbps • 802.11ac: max 433.3Mbps
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power³	• 802.11b: +14dBm minimum • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum • 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W

Technical Specifications – Networking

	<ul style="list-style-type: none"> • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth® 4.0/4.1/4.2 Wireless Card Technology	
Bluetooth® Specification	4.0/4.1/4.2 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Transmit Power	USB 2.0 compliant
Power Consumption	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported Link Topology	Microsoft Windows ACPI, and USB Bus Support
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	4.0/4.1/4.2 Compliant

Technical Specifications – Networking

Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
2. Check latest software/driver release for updates on supported security features.
3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications – Networking

Realtek RTL8852BE 802.11ax 2x2 Wi-Fi 6 + Bluetooth 5.3 Wireless Card (802.11ax 2x2, supporting gigabit data rate)¹	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac: max 866.7Mbps • 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power³	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ax HE40(2.4GHz): +10dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum

Technical Specifications – Networking

Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.5 W • Receive mode: 2 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW

Technical Specifications – Networking

	Selective Suspend: 17 mW
Electrical Interface	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported	Microsoft Windows ACPI, and USB Bus Support
Link Topology	
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	<p>ETS 300 328, ETS 300 826</p> <p>Low Voltage Directive IEC950</p> <p>UL, CSA, and CE Mark</p> <p>Peak (Tx): 330 mW</p> <p>Peak (Rx): 230 mW</p> <p>Selective Suspend: 17 mW</p>
Power Management	Microsoft Windows Bluetooth Software
Certifications	
Bluetooth Profiles Supported	<p>BT4.1-ESR 5/6/7 Compliance</p> <p>LE Link Layer Ping</p> <p>LE Dual Mode</p> <p>LE Link Layer</p> <p>LE Low Duty Cycle Directed Advertising</p> <p>LE L2CAP Connection Oriented Channels</p> <p>Train Nudging & Interlaced Scan</p> <p>BT4.2 ESR08 Compliance</p> <p>LE Secure Connection- Basic/Full</p> <p>LE Privacy 1.2 –Link Layer Privacy</p> <p>LE Privacy 1.2 –Extended Scanner Filter Policies</p> <p>LE Data Packet Length Extension</p> <p>FAX Profile (FAX)</p> <p>Basic Imaging Profile (BIP)2</p> <p>Headset Profile (HSP)</p> <p>Hands Free Profile (HFP)</p> <p>Advanced Audio Distribution Profile (A2DP)</p> <p>BT5.1</p> <p>ESR9/10 Compliance</p> <p>LE Advertisement Extensions</p> <p>Channel Selection Algo</p> <p>Limited High Duty Cycle Non-Connectable Advertising</p> <p>2Mbps LE</p> <p>LE Long Range</p>

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.
2. Check latest software/driver release for updates on supported security features.
3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications – Input/Output

INPUT/OUTPUT DEVICES

HP USB 125 (Antimicrobial)/128 Laser Mouse (China only)		
Dimensions (H x L x W)	112 x 63 x 36.2 mm (L x W x H)	
Weight	85 g	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption (typical)	100mA
	Resolution	1,200 DPI
	Sensor	Optical/ Laser USB mouse sensor
	Tracking speed	30 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s ²
Mechanical	Connector	USB
	Cable length	6 ft (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC

HP Wired Desktop 320M Mouse		
Physical Characteristics	Keys	Left/right key
	Dimensions(L x W x H)	4.09 x2.50 x 1.40 in (103.8x 63.4 x 35.5 mm)
	Weight	0.16 lb(72g)
Electrical	Operating voltage	5 VDC, +/-0.25V
	Power consumption	100 mA Max
	System interface	USB Port
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)
	EMI - RFI	European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B
Mechanical	Keycaps	0.3mm key travel
	Key actuation	75±20g
	Key life	1million cycles
	Key structure type	Tact Switch

Technical Specifications – Input/Output

	Key-leveling mechanisms	N/A		
Environmental	Operating temperature	10° to 90° C		
	Non-operating temperature	-30° C to 95° C		
	Operating humidity	N/A		
	Non-operating humidity	10% to 90% (non-condensing at ambient)		
	Operating shock	N/A		
	Non-operating shock	i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operational Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom, and Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G’s. Test also at 40 and 50G’s to find margin. Velocity change: 266lps (inch-per-second) for product mass (m) 20<m<40lbs.		
	Operating vibration	Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)
		5-350	0	0.0001
		350-500	-6	-
		500	-	0.00005
		(~0.21G _{nms})		
		Total Test time: 10 minutes		
	Non-operating vibration	Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)
5.100		0	0.015	
100-137		-6	-	
137-350		0	0.008	
350-500		-6	-	
500		-	0.0039	
Drop (out of box)	76cm on carpet, six-drop sequence			
Drop (in box)	N/A			
Approvals	CB, CE, FCC, cULus, ICES, EAC, NOM-NYCE SCT, RCM, VCCI, KC, BSMI			
Ergonomic compliance	TUVGS			

Technical Specifications – Input/Output

HP USB Business Slim Wired SmartCard CCID Keyboard		
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)
	Weight	1.32 lb (598g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	100mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CE Marking, TUV, EAC, FCC, cULus/CSAus, ICES, RCM, VCCI, KCC, BSMI	
Ergonomic compliance	ISO 9241-4, TUVGS	

Technical Specifications – Input/Output

HP 125 (Antimicrobial) Wired Keyboard (China only)		
Physical Characteristics	Keys	104/105/107/109 layout (depending upon country)
	Dimensions (L x W x H)	436 x 138 x 24.7 mm
	Weight	471g
Electrical	Operating voltage	5V +- 5%
	Power consumption	50mA
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	55±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	1.8 m
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-4° to 149° F (-20° to 65° C)
	Operating humidity	10% to 95% (non-condensing at ambient)
	Non-operating humidity	0% to 95% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI, BSMI, RCM, KCC, USB-IF, WHQL, EN/IEC 60601-1	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS	

Technical Specifications – Input/Output

HP 655 wireless Keyboard		
Physical Characteristics	Keys	104, 105, 107, 109 layouts
	Dimensions (L x W x H)	16.86 x 4.55 x 0.71 in (428.22 x 115.47 x 18.06 mm)
	Weight	0.96 lb (435g)
Electrical	Operating voltage	3 VDC, +/-5%
	Power consumption	20 mA Max (All LED on)
	System interface	2.4GHz Wireless
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Plunger, 2.0 mm key travel
	Key actuation	60±10g nominal peak force with tactile feedback
	Key life	10 million keystrokes (Life tester)
	Key structure type	Rubber dome & Membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CB, CE, FCC, cULus, ICES, IC, I TRC, TRA, CASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, MPTC, RCM, BIS, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC	
Ergonomic compliance	TUVGS	

Technical Specifications – Audio

AUDIO/MULTIMEDIA

Type	Integrated
HD Stereo Codec	Realtek ALC3252
Audio I/O Ports	Front: Headset connector supports a CTIA and OMTP style headset and is retaskable as a Line-in, Line-out, Microphone-in or Headphone-out port
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally
Multi-streaming Capable	Playback multi-streaming allows independent audio streams to be sent to/from the front jacks and integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

Technical Specifications – Power

POWER SUPPLY

Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current with Energy Efficient* Power Supply	65W≤ 1.6A Average efficiency 88% at 115V Average efficiency 89% at 230V
DC Output	+19.5V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power cord length	6.0 ft. (1.83 m)
Dimensions	90 x 51 x 28.5mm & 102 x 55 x 30mm

Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS¹

System

Dimensions	6.97 x 6.89 x 1.35 in 177 x 175 x 34.2 mm
Weight ²	2.74 lbs 1.25 kg
Volume	64 cu in 1.05 L

Packaging dimensions and weight

Dimensions	19.57 x 5.04 x 8.78 in 497 x 128 x 223 mm MPP/EPE: 19.61 x 9.25 x 5.20 in 498 x 235 x 132 mm
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Weight	7.36 lbs 3.34 kg MPP/EPE: 6.4 lbs 2.9 kg
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Palletization and Container

Pallet Profile	1 unit/carton 18 cartons/layer 5~6 layers per pallet max depending on details of air freight 90~108 units per pallet depending on details of air freight MPP/EPE: 1 unit/carton 10 cartons/layer 10~19 layers per pallet max depending on details of ground/sea freight 100~190 units per pallet depending on details of ground/sea freight
Pallet Size Loaded	45.354 x 39.13 x 57.80 in 1152 x 994 x 1468 mm MPP/EPE: 46.26 x 39.21 x 103.74 in 1175 x 996 x 2635 mm

1. Packaging material used will vary by country
2. Configured with 1 SATA Drive

After-Market Options (availability may vary by region)

AFTER MARKET OPTIONS

Type	Description	Part Number
Graphics Solutions	HP HDMI Standard Cable Kit	T6F94AA
	HP DisplayPort™ To HDMI True 4k Adapter	2JA63AA
	HP DisplayPort™ Cable Kit	VN567AA
	HP DisplayPort™ To VGA Adapter	AS615AA
	HP DisplayPort™ To DVI-D Adapter	FH973AA
	HP USB to Serial Adapter	J7B60AA
	HP HDMI to VGA Adapter	H4F02AA
Desktop Mini Accessories	HP Desktop Mini 2.5" SATA Drive Bay kit v2	13L70AA
	HP Desktop Mini LockBox V2	3EJ57AA
	HP Desktop Mini DVD-Writer ODD Expansion Module	K9Q83AA
	HP Desktop Mini Security/Dual VESA Sleeve v3	13L67AA
	HP Desktop Mini Security/Dual VESA Sleeve v3 With Power Supply Holder	13L68AA
	HP B300 PC Mounting Bracket with Power Supply Holder	7DB37AA
	HP Desktop Mini Vertical Chassis Stand	G1K23AA
	HP Integrated Work Center Stand 5	G1V61AA
Data Storage Drives	HP PCIe NVME Gen4 TLC 512GB SSD M.2 Drive	406L8AA
	HP PCIe NVME Gen4 TLC 1TB SSD M.2 Drive	406L7AA
Input Devices	HP Wired Desktop 320K Keyboard	9SR37AA
	HP USB Business Slim SmartCard CCID Keyboard	Z9H48AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA
	HP 128 Laser Wired Mouse	265D9AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo (China Only)	286K3AA
	HP Mouse Pad	AT485AA

After-Market Options (availability may vary by region)

Memory	HP 4GB DDR4-3200 SODIMM	13L79AA
	HP 8GB DDR4-3200 SODIMM	13L77AA
	HP 16GB DDR4-3200 SODIMM	13L75AA
	HP 32GB DDR4-3200 SODIMM	13L73AA
Multimedia Devices	HP S101 Speaker Bar	5UU40AA
	HP Stereo 3.5mm Headset G2	428K7AA
	HP Stereo USB Headset G2	428K6AA
Security Devices	HP Keyed Cable Lock 10mm	T1A62AA
	HP Master Keyed Cable Lock 10mm	T1A63AA
Stands and Mounting Accessories	HP B560 PC Mounting Bracket	763U8AA
	HP B200 PC Mounting Bracket	762T5AA
	HP B250 PC Mounting Bracket	8RA46AA
	HP B300 PC Mounting Bracket	2DW53AA
	HP Quick Release Bracket 2	6KD15AA

Change Log

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Date of change:	Version History:		Description of change:
August 29, 2023	From v1 to v2	Correction	Packaging Weight corrected
October 30, 2023	From v2 to v3	Update	Security section updated
November 1, 2023	From v3 to v4	Removal	“Shipped with Windows 10” removed
May 3, 2024	From v4 to v5	Update	2.5 inch SATA Hard Disk Drives section updated / HP Desktop Mini Port Cover v3 from AMO section
June 17, 2025	From v5 to v6	Addition	Intel® Core™ i5-1334U Processor added
October 14, 2025	From v6 to v7	Addition	BIOS added to Software section